

20th Anniversary of KSDT
KISM 2022
Korean International Semiconductor Conference on Manufacturing Technology 2022
November 13-16, 2022 | Paradise Hotel Busan (Haeundae Beach), Busan, Korea

Session Title:	[ME1] 3D Package I
Session Date:	November 14 (Mon.), 2022
Session Time:	13:00-14:25
Session Room:	Room E (Grand Ballroom 3, 2F)
Session Chair:	Prof. Changhwan Choi (Hanyang Univ., Korea)

[ME1-1] 13:00-13:20

2.5D/ 3D Advanced Interconnection Technology Development and Challenges
Lam Tak Wing, Percy (ASMPT Hong Kong Limited, Hong Kong)

[ME1-2] 13:20-13:40

Advanced Packaging Trends and Technologies of Heterogeneous Integration
Gu-Sung Kim (Kangnam Univ., Korea)

[ME1-3] [Plenary] 13:40-14:25

Chips, Dies, Chiplets and Dielets and Heterogeneous Integration (of course!)
Subramania S. Iyer (UCLA, USA)